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ESI Showcases Latest Addition to Flex PCB Processing Portfolio

New RedStone™ Flex PCB Processing System Highlighted at the International Printed Circuit and APEX South China Fair

PORTLAND, Ore., Jan. 06, 2017 (GLOBE NEWSWIRE) -- Electro Scientific Industries, Inc. (Nasdaq:ESIO), an innovator in laser-based manufacturing solutions for the micro-machining industry, highlighted its new low-cost RedStone™ PCB laser processing system at the Hong Kong Printed Circuit Association's (HKPCA) trade show in Shenzhen, China, December 7-9. ESI's nViant™ solution for HDI PCB manufacturing was also highlighted.

The RedStone system is ESI's latest addition to its market-leading portfolio of flexible PCB laser processing solutions, and is engineered to cost-effectively address a specific range of applications and processing capabilities. For FPC manufacturers considering the adoption of laser processing for flex PCB, RedStone provides a capable low cost-of-entry solution to supplement their mechanical drilling capabilities, and enables them to offer an additional set of production-oriented laser processing services. For those who have already integrated flexible PCB laser processing into their production flow, RedStone offers optimized production targeting specific applications, such as through-via drilling and through-cut routing.

"RedStone is designed, first and foremost, around optimizing production for flex PCB processors," stated Mike Jennings, Director of Product Marketing for ESI's Flex Products Division. "For customers looking to gain application-specific processing efficiencies through pairing the right tool to the right job, or the addition of a laser processing option, RedStone is the right tool. It rounds-out our portfolio of FPC solutions, as a versatile platform offered at an entry level of affordability, and it was a popular topic with attendees at the show."

RedStone delivers an optimal combination of laser type and laser control capabilities to address the processing of basic applications requiring extra power or more repetitions to ensure that the process is robust and delivers high yield. It extends the breadth of a solutions portfolio that already includes the industry's most popular line of flex PCB processing systems, a CO₂-laser-based processing system for affordable HDI PCB manufacturing, and high-volume low cost-of-ownership solutions for IC packaging.

Early market adoption of the RedStone system has already been promising, with initial system orders placed with Asia-based customers.

RedStone is available through ESI directly, as well as through ESI channel partners.

About ESI, Inc.

ESI's integrated solutions allow industrial designers and process engineers to control the power of laser light to transform materials in ways that differentiate their consumer electronics, wearable devices, semiconductor circuits and high-precision components for market advantage. ESI's laser-based manufacturing solutions feature the micro-machining industry's highest precision and speed, and target the lowest total cost of ownership. ESI is headquartered in Portland, Ore., with global operations from the Pacific Northwest to the Pacific Rim. More information is available at www.esi.com.

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Source: Electro Scientific Industries, Inc.

